

### In the Claims

This listing of claims will replace all prior versions, and listings, of claims.

### Listing of Claims

1. (Currently amended) A bonding pad structure, comprising:  
  
a bonding pad substantially surrounded and insulated by a dielectric layer, wherein the bonding pad comprises at least one first conductive layer having a wiring layer with a stripe layout and a first edge portion, a second conductive layer having a wire bonding portion and a second edge portion and a plurality of plugs electrically connecting the wiring layer and the wire bonding portion; and  
  
a conductive structure surrounding the wire bonding portion, connecting the first edge portion and the second edge portion.
2. (Original) The structure according to claim 1, further comprising:  
  
an electrostatic discharge (ESD) protection device electrically connected to the first conductive layer.
3. (Original) The structure according to claim 1, wherein a material of the dielectric layer is a low dielectric constant material.
4. (Original) The structure according to claim 1, wherein the first conductive layer is a metal layer.
5. (Original) The structure according to claim 1, wherein the second conductive layer is a metal layer.

6. (Original) The structure according to claim 1, wherein the conductive structure is an array of metal plugs.

7. (Canceled).

8. (Currently amended) A bonding pad structure, comprising:  
a substrate having an interlevel dielectric (ILD) layer thereon,  
a bonding pad formed on the ILD layer and substantially surrounded and insulated by an intermetal dielectric (IMD) layer, wherein the bonding pad comprises at least one metal layer having a wiring layer with a stripe layout and a first edge portion, a bonding metal layer having a wire bonding portion and a second edge portion and a plurality of plugs electrically connecting the wiring layer and the wire bonding portion; and  
a conductive structure surrounding the wire bonding portion, connecting the first edge portion and the second edge portion.

9. (Original) The structure according to claim 8, further comprising:  
an electrostatic discharge (ESD) protection device electrically connected to the first conductive layer

10. (Original) The structure according to claim 8, wherein a material of the IMD layer is a low dielectric constant material.

11. (Original) The structure according to claim 8, wherein the conductive structure is an array of metal plugs.

12. (Canceled).

13. – 23. Canceled.

24. (new) A bonding pad structure, comprising:

a bonding pad substantially surrounded and insulated by a dielectric layer, wherein the bonding pad comprises at least one first conductive layer having a wiring layer with a stripe layout and a first edge portion, a second conductive layer having a wire bonding portion and a second edge portion and a plurality of plugs electrically connecting the wiring layer and the wire bonding portion; and

an array of metal plugs connecting the first edge portion and the second edge portion.

25. (new) The structure according to claim 24, further comprising:

an electrostatic discharge (ESD) protection device electrically connected to the first conductive layer.

26. (new) The structure according to claim 24, wherein a material of the dielectric layer is a low dielectric constant material.

27. (new) The structure according to claim 24, wherein the first conductive layer is a metal layer.

28. (new) The structure according to claim 24, wherein the second conductive layer is a metal layer.